

Elektronų pernaša 2D AlGaN/(AlN)/GaN ir 3D GaN dariniuose stipriame elektriniame lauke

Electron transport in 2D AlGaN/(AlN)/GaN and 3D GaN structures in a strong electric field

Linus Ardaravičius, Oleg Kiprijanovič, Emilis Šermukšnis, Artūr Šimukovič,
Justinas Jorudas, Liudvikas Subačius, Irmantas Kašalynas
Center for Physical Sciences and Technology, Saulėtekio av. 3, LT-10257, Vilnius
linas.ardaravicius@ftmc.lt

Gallium nitride (GaN) has many attractive properties for high-power and high-frequency applications due to a wide bandgap of 3.4 eV and a high electron peak velocity of $\sim 3 \times 10^7$ cm/s achieved at high electric fields [1]. In particular, the velocity of two-dimensional electron gas (2DEG) in nitride-based heterostructures varies from 1×10^7 to 3×10^7 cm/s depending on the presence of barrier layer [2]. In this work, layers for the AlGaN/AlN/GaN sample (U79) were grown on 6H-polytype SiC substrate. A nominally undoped $\text{Al}_{0.25}\text{Ga}_{0.75}\text{N}$ barrier layer was grown capping it with GaN and SiN_x passivation layers. A similar structure, but without an AlN spacer - AlGaN/GaN (U78) was developed on a 4H-polytype SiC substrate where a $\text{Al}_{0.25}\text{Ga}_{0.75}\text{N}$ barrier was capped by a GaN layer. Lightly doped GaN epitaxial layers were grown on semi-insulating GaN substrates. The ohmic contacts were fabricated of a Ti/Al/Ni/Au metal stack annealed in nitrogen ambient. The mesas were formed either by plasma reactive ion etching or by implantation of Al ions into a depth. The TLMs of width $w = 250 \mu\text{m}$ and of length $L = 6, 12.5, 25, 35, 45, 55, 65 \mu\text{m}$ were used to evaluate the contact resistance $R_c = 1\text{--}22.5 \Omega$ at low electric fields. The Hall effect experiments in Van der Paw geometry at temperature of 300 K revealed the density n and mobility μ values of 2DEG channels in used samples to be of $8.3 \times 10^{12} \text{ cm}^{-2}$ and $9.3 \times 10^{12} \text{ cm}^{-2}$ and of $1.9 \times 10^3 \text{ cm}^2/\text{Vs}$ and $1.9 \times 10^3 \text{ cm}^2/\text{Vs}$, respectively. The GaN epilayers with a thickness of $d = 10 \mu\text{m}$ demonstrated three-dimensional electron density (3DEG) and low-field mobility values of $1.1 \times 10^{16} \text{ cm}^{-3}$ and $1021 \text{ cm}^2/\text{Vs}$ at 300 K. More details about the device growth and processing have been reported elsewhere [3, 4]. Current-voltage (I - U) characteristics were measured at room temperature using voltage pulse duration of 2 ns and 3 ns for the samples from U79 and U78, respectively, where the average electric field was determined as $E=U/L$. The pulse duration for the GaN sample was 20 ns. The use of nanosecond duration pulses enables minimization of lattice self-heating effects and avoiding of space-charge domain formation in GaN [5]. Current density value of 1.24 A/mm at the highest field were reached for U79 with a $45 \mu\text{m}$ channel length while the highest current density value of 1.8 A/mm were measured for U78 with a $35 \mu\text{m}$ channel length. The highest current density of 320 A/mm² was measured for the 3D GaN. The strongest electric field of 75 kV/cm was applied to U78 with a channel length of 12.5 μm and showed current saturation. Electron drift velocity v_{dr} was estimated from data of measured current density j and the Hall electron density ($v_{\text{dr}} = j/en$, where e is elementary charge) with a highest value of 1.2×10^7 cm/s

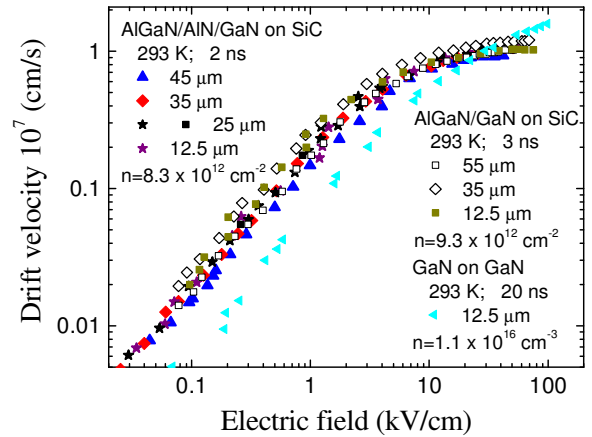


Fig. 1. Electron drift velocity dependence on the average applied electric field at room temperature in AlGaN/(AlN)/GaN heterostructures grown on SiC substrate and GaN grown on GaN substrate.

at 69 kV/cm for U78 heterostructure while the lowest value of 0.9×10^7 cm/s at 42 kV/cm was obtained for U79 heterostructure (Fig. 1). The electron velocity in the hetero-structures grown without the AlN spacer on SiC substrate was found to be 10–20 % lower than that measured for AlGaN/GaN structures but grown on sapphire substrate [2]. The highest electron velocity of 1.6×10^7 cm/s at 95 kV/cm was attained for the GaN. The drift velocity at high fields in the 2D GaN channel is lower than that in the 3D GaN as a result of stronger hot-phonon effect. Self-heating of the contacts leading to the increase of the contact resistance can play the role in determining the excess noise temperature in GaN-based heterostructures [4].

Keywords: electric field strength, nanosecond electrical pulses, electron drift velocity, GaN, AlGaN/(AlN)/GaN, 2D-3D electron gas

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